

C2225C332JFGACTU

Aliases (C2225C332JFGAC7800) SMD Comm COG HV, Ceramic, 3,300 pF, 5%, 1,500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2225, 3.2 mm



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	300 mg
Shelf Life	78 Weeks
MSL	1

3,300 pF

100 GOhms

Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.2mm MIN
В	0.6mm +/-0.35mm

/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
/-0.4mm	Tolerance	5%
'-0.15mm	Voltage DC	1500 VDC
IN	Dielectric Withstanding Voltage	1,800 VDC
/-0.35mm	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

Specifications

Insulation Resistance

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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